



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE
FOR REFLOW SOLDERING

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

RECEIVED

APR 8 - 2002

IC 1700

Dear Sir:

Pursuant to the requirements of 37 CFR §§1.56 and 1.97, the attention of the Examiner is directed to the documents listed on the attached Form PTO-1449. A copy of each of the listed documents is attached. Neither this Statement nor the listing of these documents on Form PTO-1449 is an admission that these documents are prior art as to the Applicants nor a representation that a search has been made or that no more pertinent documents exist.

The Applicants' representative certifies that the attached documents were cited in a communication from the European Patent Office in a counterpart foreign patent application not more than

three months before the filing date of this Information Disclosure Statement. A copy of the search report for the foreign patent application is also attached.

The Applicants respectfully request that the attached documents be considered by the Examiner and made of record in the referenced patent application.

Respectfully submitted,



Michael Tobias
Registration Number 32,948

Suite 304
1730 K Street, N.W.
Washington, D.C. 20006
Telephone: (301) 587-6541
Facsimile: (301) 587-6623
Date: 1/23/02